

# SOT1429-1

plastic, heatsink small outline package; 6 leads(flat)

8 February 2016

Package information

## 1. Package summary

Terminal position code	D (double)
Package type descriptive code	HSOP6F
Package type industry code	HSOP6F
Package style descriptive code	HSOP (heatsink small outline package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	30-10-2014

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		20.52	-	20.57	20.62	mm
E	package width		9.91	-	9.96	10.01	mm
A	seated height		-	-	-	3.9	mm
e	nominal pitch		-	-	10	-	mm
n <sub>2</sub>	actual quantity of termination		-	-	6	-	



2. Package outline

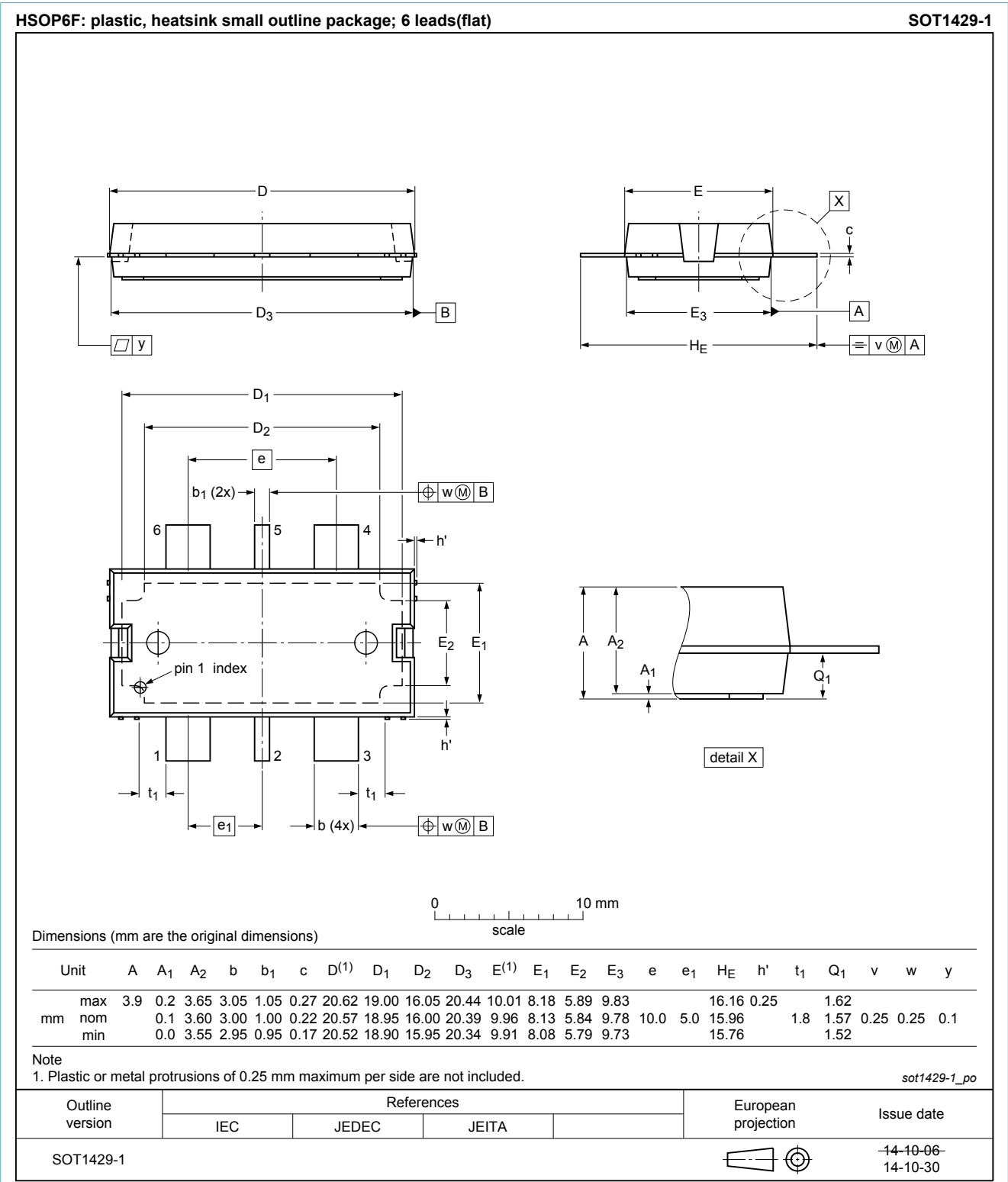


Fig. 1. Package outline HSOP6F (SOT1429-1)

### 3. Legal information

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